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Part Number: [0739446016](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 72 Circuits

Documents:
[3D Model](#) [Product Specification PS-73670-9999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73944](#)
Application Backplane
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part Yes
Keying to Mating Part Yes
Material - Metal Phosphor Bronze, Stainless Steel
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.138 In
PC Tail Length (mm) 3.50 mm
PCB Locator Yes
PCB Retention None
PCB Thickness Recommended (in) 0.098 In
PCB Thickness Recommended (mm) 2.50 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Pitch - Term. Interface (in) 0.079 In
Pitch - Term. Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Polarized to PCB No



Series

image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73944Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

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NOTES:

1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. SEE SHEET 2 FOR SPECIFIC MATERIAL NUMBERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRWN:MSI BARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
		mmINCH		DRAWN BY JB INGHAM		DATE 1998/01/14	SALES ASSY HDM BACKPLANE POLAR/GUIDE OPTION SOLDER TAIL VERSION	
		4 PLACES ± --- ± ---		CHECKED BY SREED		DATE 1998/01/14		
		3 PLACES ± --- ± ---		APPROVED BY CBIXLER		DATE 1998/01/14		
		2 PLACES ± 0.05 ± ---		1 PLACE ± 0.10 ± ---		MOLEX INCORPORATED		
ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE B		SEE CHART		SD-73944-001		1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

LOCATION A



ROW F

ROW A

LOCATION B



LOCATION B

REF. MATERIAL NUMBER 73944-1009
GUIDE PIN IS IN LOCATION A
POLARIZING KEY IS IN LOCATION B, POSITION E

REF. MATERIAL NUMBER 73944-1008
GUIDE PIN IS IN LOCATION B
POLARIZING KEY IS IN LOCATION A, POSITION E

LOCATION A

MATERIAL NUMBER ASSIGNMENT

73944- * * * *

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	31.60	22.00	2.00
1	144	55.60	46.00	2.00
2	72	31.60	22.00	2.50
3	144	55.60	46.00	2.50
4	72	31.60	22.00	3.00
5	144	55.60	46.00	3.00
6	72	31.60	22.00	3.50
7	144	55.60	46.00	3.50

NUMBER	DIM "M"
0	5.00
1	5.50
2	6.00

NUMBER	GUIDE POST LOCATION	POLAR KEY POSITION
00	B	A
01	A	
02	B	
03	A	B
04	B	
05	A	C
06	B	
07	A	D
08	B	
09	A	E
10	B	
11	A	F
12	B	
13	A	G
14	B	
15	A	H
16	B	
17	A	N/A
18	N/A	

SEE SHEET 1
EC No. U81577
DRWN: BINGHAM 98/02/03
CHK: REED 98/02/03
APPR: BIXLER 98/02/03

DESCRIPTION
REV

QUALITY SYMBOLS
MAJOR
CRITICAL

GENERAL TOLERANCES:
(UNLESS SPECIFIED)
mm INCH
4 PLACES ±0. ±.
3 PLACES ±0. ±.
2 PLACES ±0. N/A ±.
1 PLACE ±0. N/A ±.
ANGULAR: ± 1/2°
DRAFT WHERE APPLICABLE MUST
REMAIN WITHIN DIMENSIONS

SCALE
2 : 1
DESIGN UNITS
mm INCH
DRAWN BY & DATE
JBINGHAM 98/01/14
CHECKED BY & DATE
SREED 98/01/14
APPROVED BY & DATE
CBIXLER 98/01/14
CAD FILENAME
S73944X2.DGN

TITLE: SALES ASSY, HDM BACKPLANE
POLAR/GUIDE OPTION
SOLDER TAIL VERSION
MOLEX INCORPORATED
MATERIAL NO. SEE CHART
DRAWING NO. SD-73944-001
SHEET NO. 2
SIZE B